

The documentation and process conversion measures necessary to comply with this revision shall be completed by 22 July 2010.

INCH-POUND

MIL-PRF-19500/685E
22 April 2010
SUPERSEDING
MIL-PRF-19500/685D
w/AMENDMENT 1
11 November 2009

PERFORMANCE SPECIFICATION SHEET

SEMICONDUCTOR DEVICE, FIELD EFFECT RADIATION HARDENED
TRANSISTOR, N-CHANNEL, SILICON, TYPES 2N7475T1, 2N7476T1, AND 2N7477T1
(TOTAL DOSE AND SINGLE EVENT EFFECTS),
JANTXVR AND JANSR

This specification is approved for use by all Departments and Agencies of the Department of Defense.

The requirements for acquiring the product described herein shall consist of this specification sheet and MIL-PRF-19500.

1. SCOPE

1.1 Scope. This specification covers the performance requirements for N-Channel, enhancement-mode, MOSFET, radiation hardened (total dose and single event effects (SEE)), power transistors, with avalanche energy maximum rating (E_{AS}) and maximum avalanche current (I_{AS}). Two levels of product assurance are provided for each device type as specified in MIL-PRF-19500. See 6.5 for JANHC and JANKC die versions.

1.2 Physical dimensions. See figure 1, (TO-254AA).

1.3 Maximum ratings. T_A = +25°C, unless otherwise specified.

Type	P _T (1) T _C = +25°C	P _T T _A = +25°C	R _{θJC} (2)	V _{DS}	V _{DG}	V _{GS}	I _{D1} (3) (4) T _C =+25°C	I _{D2} (3) (4) T _C = +100°C	I _S	I _{DM} (5)	T _J and T _{STG}
	<u>W</u>	<u>W</u>	<u>°C/W</u>	<u>V dc</u>	<u>V dc</u>	<u>V dc</u>	<u>A dc</u>	<u>A dc</u>	<u>A dc</u>	<u>A (pk)</u>	<u>°C</u>
2N7475T1	208	3.0	0.60	130	130	±20	45	45	45	180	-55
2N7476T1	208	3.0	0.60	200	200	±20	45	29	45	180	to
2N7477T1	208	3.0	0.60	250	250	±20	37	23.5	37	148	+150

- (1) Derate linearly 1.67 W/°C for T_C > +25°C.
- (2) See figure 2, thermal impedance curves.
- (3) The following formula derives the maximum theoretical I_D specs. I_D is limited to 45 A by package and device construction:

$$I_D = \sqrt{\frac{T_{JM} - T_C}{(R_{\theta JC}) \times (R_{DS(on)} \text{ at } T_{JM})}}$$

- (4) See figure 3, maximum drain current graph.
- (5) I_{DM} = 4 X I_{D1} as defined in note (3).

* Comments, suggestions, or questions on this document should be addressed to Defense Supply Center, Columbus, ATTN: DSCC-VAC, P.O. Box 3990, Columbus, OH 43218-3990, or emailed to Semiconductor@dsc.dla.mil. Since contact information can change, you may want to verify the currency of this address information using the ASSIST Online database at <https://assist.daps.dla.mil/>.

1.4 Primary electrical characteristics at $T_C = +25^\circ\text{C}$.

Type	Min $V_{(BR)DSS}$ $V_{GS} = 0$ $I_D = 1.0 \text{ mA}$ dc	$V_{GS(TH)1}$ $V_{DS} \geq V_{GS}$ $I_D = 1.0 \text{ mA}$ dc	Max I_{DSS1} $V_{GS} = 0$ $V_{DS} = 80$ percent of rated V_{DS}	Max $r_{DS(on)}$ (1) $V_{GS} = 12\text{V}$, $I_D = I_{D2}$		E_{AS}
				$T_J = +25^\circ\text{C}$	$T_J = +150^\circ\text{C}$	
	<u>V dc</u>	<u>V dc</u> Min Max	<u>μA dc</u>	<u>Ω</u>	<u>Ω</u>	<u>mJ</u>
2N7475T1	130	2.5 4.5	10	0.0145	0.033	432
2N7476T1	200	2.5 4.5	10	0.044	0.101	256
2N7477T1	250	2.5 4.5	10	0.061	0.153	258

(1) Pulsed (see 4.5.1).

2. APPLICABLE DOCUMENTS

2.1 General. The documents listed in this section are specified in sections 3, 4, or 5 of this specification. This section does not include documents cited in other sections of this specification or recommended for additional information or as examples. While every effort has been made to ensure the completeness of this list, document users are cautioned that they must meet all specified requirements of documents cited in sections 3, 4, or 5 of this specification, whether or not they are listed.

2.2 Government documents.

2.2.1 Specifications, standards, and handbooks. The following specifications, standards, and handbooks form a part of this document to the extent specified herein. Unless otherwise specified, the issues of these documents are those cited in the solicitation or contract.

DEPARTMENT OF DEFENSE SPECIFICATIONS

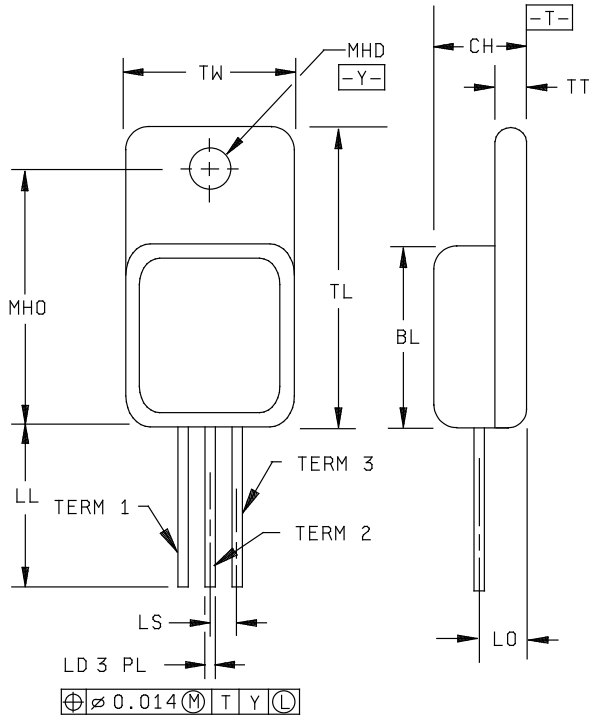
MIL-PRF-19500 - Semiconductor Devices, General Specification for.

DEPARTMENT OF DEFENSE STANDARDS

MIL-STD-750 - Test Methods for Semiconductor Devices.

* (Copies of these documents are available online at <https://assist.daps.dla.mil/quicksearch/> or <https://assist.daps.dla.mil/> or from the Standardization Document Order Desk, 700 Robbins Avenue, Building 4D, Philadelphia, PA 19111-5094.)

2.3 Order of precedence. Unless otherwise noted herein or in the contract, in the event of a conflict between the text of this document and the references cited herein, the text of this document takes precedence. Nothing in this document, however, supersedes applicable laws and regulations unless a specific exemption has been obtained.



Ltr	Dimensions				Notes
	Inches		Millimeters		
	Min	Max	Min	Max	
BL	.535	.545	13.59	13.84	
CH	.249	.260	6.32	6.60	
LD	.035	.045	0.89	1.14	
LL	.510	.570	12.95	14.48	5
LO	.150 BSC		3.81 BSC		
LS	.150 BSC		3.81 BSC		
MHD	.139	.149	3.53	3.78	4
MHO	.665	.685	16.89	17.40	
TL	.790	.800	20.07	20.32	
TT	.040	.050	1.02	1.27	
TW	.535	.545	13.59	13.84	
Term 1	Drain				
Term 2	Source				
Term 3	Gate				

NOTES:

1. Dimensions are in inches.
2. Millimeters are given for general information only.
3. All terminals are isolated from case.
4. In accordance with ASME Y14.5M, diameters are equivalent to ϕ x symbology.
5. Protrusion thickness of ceramic eyelets included in dimension LL.

FIGURE 1. Dimensions and configuration (TO-254AA).

3. REQUIREMENTS

3.1 General. The individual item requirements shall be as specified in MIL-PRF-19500 and as modified herein.

3.2 Qualification. Devices furnished under this specification shall be products that are manufactured by a manufacturer authorized by the qualifying activity for listing on the applicable qualified manufacturers list (QML) before contract award (see 4.2 and 6.3).

3.3 Abbreviations, symbols, and definitions. Abbreviations, symbols, and definitions used herein shall be as specified in MIL-PRF-19500.

3.4 Interface and physical dimensions. The interface and physical dimensions shall be as specified in MIL-PRF-19500, and figure 1 (TO-254AA) herein. Methods used for electrical isolation of the terminals shall employ materials that contain a minimum of 90 percent Al₂O₃ (ceramic).

3.4.1 Lead formation and finish. Lead finish shall be solderable in accordance with MIL-STD-750, MIL-PRF-19500 and herein. Where a choice of finish is desired, it shall be specified in the acquisition document (see 6.2). When lead formation is performed, as a minimum, the vendor shall perform 100 percent hermetic seal in accordance with screen 14 of MIL-PRF-19500 and 100 percent dc testing in accordance with table I, subgroup 2 herein.

3.4.2 Internal construction. Multiple chip construction shall not be permitted.

3.5 Marking. Marking shall be in accordance with MIL-PRF-19500. At the option of the manufacturer, marking of the country of origin may be omitted from the body, but shall be retained on the initial container.

3.6 Electrostatic discharge protection. The devices covered by this specification require electrostatic discharge protection.

3.6.1 Handling. MOS devices must be handled with certain precautions to avoid damage due to the accumulation of static charge. However, the following handling practices are recommended (see 3.6).

- a. Devices should be handled on benches with conductive handling devices.
- b. Ground test equipment, tools, and personnel handling devices.
- c. Do not handle devices by the leads.
- d. Store devices in conductive foam or carriers.
- e. Avoid use of plastic, rubber, or silk in MOS areas.
- f. Maintain relative humidity above 50 percent if practical.
- g. Care should be exercised during test and troubleshooting to apply not more than maximum rated voltage to any lead.
- h. Gate must be terminated to source, $R \leq$ or 100 k Ω , whenever bias voltage is applied drain to source.

3.7 Electrical performance characteristics. Unless otherwise specified herein, the electrical performance characteristics are as specified in 1.3, 1.4 and table I herein.

3.8 Electrical test requirements. The electrical test requirements shall be as specified in table I.

3.9 Workmanship. Semiconductor devices shall be processed in such a manner as to be uniform in quality and shall be free from other defects that will affect life, serviceability, or appearance.

4. VERIFICATION

4.1 Classification of inspections. The inspection requirements specified herein are classified as follows:

- a. Qualification inspection (see 4.2).
- b. Screening (see 4.3).
- c. Conformance inspection (see 4.4 and tables I and II).

4.2 Qualification inspection. Qualification inspection shall be in accordance with MIL-PRF-19500 and as specified herein. Alternate flow is allowed for qualification inspection in accordance with figure 4 of MIL-PRF-19500.

4.2.1 Group E qualification. Group E inspection shall be performed for qualification or re-qualification only. In case qualification was awarded to a prior revision of the specification sheet that did not request the performance of table III tests, the tests specified in table III herein that were not performed in the prior revision shall be performed on the first inspection lot of this revision to maintain qualification.

4.2.1.1 SEE. Design capability shall be tested on the initial qualification and thereafter whenever a major die design or process change is introduced. End-point measurements shall be in accordance with table II.

MIL-PRF-19500/685E

4.3 Screening (JANS and JANTXV). Screening shall be in accordance with table E-IV of MIL-PRF-19500 and as specified herein. The following measurements shall be made in accordance with table I herein. Devices that exceed the limits of table I herein shall not be acceptable.

Screen (see table E-IV of MIL-PRF-19500) (1) (2)	Measurement	
	JANS	JANTXV
(3)	Gate stress test (see 4.3.1).	Gate stress test (see 4.3.1).
(3)	Method 3470 of MIL-STD-750, (see 4.3.2), E _{AS} test.	Method 3470 of MIL-STD-750, (see 4.3.2), E _{AS} test.
(3) 3c	Method 3161 of MIL-STD-750, thermal impedance (see 4.3.3).	Method 3161 of MIL-STD-750, thermal impedance (see 4.3.3).
9	Subgroup 2 of table I herein I _{DSS1} , I _{GSSF1} , I _{GSSR1} , as a minimum.	Not applicable.
10	Method 1042 of MIL-STD-750, test condition B.	Method 1042 of MIL-STD-750, test condition B.
11	I _{GSSF1} , I _{GSSR1} , I _{DSS1} , r _{DS(ON)1} , V _{GS(TH)1} Subgroup 2 of table I herein. ΔI _{GSSF1} = ±20 nA dc or ±100 percent of initial value, whichever is greater. ΔI _{GSSR1} = ±20 nA dc or ±100 percent of initial value, whichever is greater. ΔI _{DSS1} = ±10 μA dc or ±100 percent of initial value, whichever is greater.	I _{GSSF1} , I _{GSSR1} , I _{DSS1} , r _{DS(ON)1} , V _{GS(TH)1} Subgroup 2 of table I herein.
12	Method 1042 of MIL-STD-750, test condition A.	Method 1042 of MIL-STD-750, test condition A.
13	Subgroups 2 and 3 of table I herein. ΔI _{GSSF1} = ±20 nA dc or ±100 percent of initial value, whichever is greater. ΔI _{GSSR1} = ±20 nA dc or ±100 percent of initial value, whichever is greater. ΔI _{DSS1} = ±10 μA dc or ±100 percent of initial value, whichever is greater. Δr _{DS(ON)1} = ±20 percent of initial value. ΔV _{GS(TH)1} = ±20 percent of initial value.	Subgroups 2 and 3 of table I herein. ΔI _{GSSF1} = ±20 nA dc or ±100 percent of initial value, whichever is greater. ΔI _{GSSR1} = ±20 nA dc or ±100 percent of initial value, whichever is greater. ΔI _{DSS1} = ±10 μA dc or ±100 percent of initial value, whichever is greater. Δr _{DS(ON)1} = ±20 percent of initial value. ΔV _{GS(TH)1} = ±20 percent of initial value.

- (1) At the end of the test program, I_{GSSF1}, I_{GSSR1}, and I_{DSS1} are measured.
- (2) An out-of-family program to characterize I_{GSSF1}, I_{GSSR1}, I_{DSS1}, and V_{GS(TH)1} shall be invoked.
- (3) Shall be performed anytime after temperature cycling, screen 3a; and does not need to be repeated in screening requirements.

4.3.1 Gate stress test. Apply $V_{GS} = -24$ V minimum for $t = 250$ μ s minimum.

4.3.2 Single pulse avalanche energy (E_{AS}).

- a. Peak current $I_{AS} = I_{D1}$.
- b. Gate voltage (V_{GS}) 12 V.
- c. Gate to source resistor (R_{GS}) $25\Omega \leq R_{GS} \leq 200\Omega$.
- d. Initial case temperature (T_c) $+25^\circ\text{C}, +10^\circ\text{C}, -5^\circ\text{C}$.
- e. Inductance (L) $\left[\frac{2E_{AS}}{(I_{D1})^2} \right] \left[\frac{V_{BR} - V_{DD}}{V_{BR}} \right]$ mH minimum.
- f. Number of pulses to be applied 1 pulse minimum.
- g. Supply voltage (V_{DD}) $V_{DD} = 50$ V dc.

4.3.3 Thermal impedance. The thermal impedance measurements shall be performed in accordance with method 3161 of MIL-STD-750 using the guidelines in that method for determining I_M, I_H, t_H, t_{SW} , (and V_H where appropriate). Measurement delay time (t_{MD}) = 70 μ s max. See table III, group E, subgroup 4 herein.

4.4 Conformance inspection. Conformance inspection shall be in accordance with MIL-PRF-19500 and as specified herein.

4.4.1 Group A inspection. Group A inspection shall be conducted in accordance with table E-V of MIL-PRF-19500 and table I herein.

4.4.2 Group B inspection. Group B inspection shall be conducted in accordance with the conditions specified for subgroup testing in table E-VIA (JANS) and table E-VIB (JANTXV) of MIL-PRF-19500, and as follows. Electrical measurements (end-points) shall be in accordance with table I, subgroup 2 herein.

4.4.2.1 Group B inspection, table E-VIA (JANS) of MIL-PRF-19500.

<u>Subgroup</u>	<u>Method</u>	<u>Condition</u>
B3	1051	Test condition G, 100 cycles.
B3	2077	SEM.
B4	1042	Intermittent operation life, condition D, 2,000 cycles. No heat sink or forced-air cooling on the device shall be permitted during the on cycle. $t_{on} = 30$ seconds minimum.
B5	1042	Accelerated steady-state gate bias, condition B, $V_{GS} = \text{rated}$; $T_A = +175^\circ\text{C}$, $t = 24$ hours minimum; or $T_A = +150^\circ\text{C}$, $t = 48$ hours minimum.
B5	1042	Accelerated steady-state reverse bias, condition A, $V_{DS} = \text{rated}$; $T_A = +175^\circ\text{C}$, $t = 120$ hours minimum; or $T_A = +150^\circ\text{C}$, $t = 240$ hours minimum.
B5	2037	Bond strength, test condition D.

4.4.2.2 Group B inspection, table E-VIB (JANTXV) of MIL-PRF-19500.

<u>Subgroup</u>	<u>Method</u>	<u>Condition</u>
B2	1051	Test condition G, 25 cycles.
B3	1042	Intermittent operation life, condition D, 2,000 cycles. No heat sink or forced-air cooling on the device shall be permitted during the on cycle. $t_{on} = 30$ seconds minimum.
B3	2037	Test condition D. All internal bond wires for each device shall be pulled separately.

4.4.3 Group C inspection. Group C inspection shall be conducted in accordance with the conditions specified for subgroup testing in table E-VII of MIL-PRF-19500 and as follows. Electrical measurements (end-points) shall be in accordance with table I, subgroup 2 herein.

<u>Subgroup</u>	<u>Method</u>	<u>Condition</u>
C2	2036	Test condition A; weight = 10 pounds, $t = 10$ s.
C5	3161	See 4.3.3, $R_{\theta JC} = 0.60^{\circ}\text{C/W}$.
C6	1042	Intermittent operation life, condition D, 6,000 cycles. No heat sink or forced-air cooling on the device shall be permitted during the on cycle. $t_{on} = 30$ seconds minimum.

4.4.4 Group D inspection. Group D inspection shall be conducted in accordance with table E-VIII of MIL-PRF-19500 and table II herein.

4.4.5 Group E inspection. Group E inspection shall be conducted in accordance with the conditions specified for subgroup testing in table E-IX of MIL-PRF-19500 and as specified in table III herein. Electrical measurements (end-points) shall be in accordance with table I, subgroup 2 herein.

4.5 Methods of inspection. Methods of inspection shall be as specified in the appropriate tables and as follows.

4.5.1 Pulse measurements. Conditions for pulse measurement shall be as specified in section 4 of MIL-STD-750.

TABLE I. Group A inspection.

Inspection <u>1/</u>	MIL-STD-750		Symbol	Limits		Unit
	Method	Condition		Min	Max	
<u>Subgroup 1</u>						
Visual and mechanical inspection	2071					
<u>Subgroup 2</u>						
Thermal impedance <u>2/</u>	3161	See 4.3.3	$Z_{\theta JC}$			°C/W
Breakdown voltage drain to source	3407	$V_{GS} = 0$, $I_D = 1$ mA dc, bias condition C	$V_{(BR)DSS}$			
2N7475T1				130		V dc
2N7476T1				200		V dc
2N7477T1				250		V dc
Gate to source voltage (threshold)	3403	$V_{DS} \geq V_{GS}$, $I_D = 1$ mA dc	$V_{GS(TH)1}$	2.5	4.5	V dc
Gate current	3411	$V_{GS} = +20$ V dc, bias condition C, $V_{DS} = 0$	I_{GSSF1}		+100	nA dc
Gate current	3411	$V_{GS} = -20$ V dc, bias condition C, $V_{DS} = 0$	I_{GSSR1}		-100	nA dc
Drain current	3413	$V_{GS} = 0$, bias condition C, $V_{DS} = 80$ percent of rated V_{DS}	I_{DSS1}		10	μA dc
Static drain to source on-state resistance	3421	$V_{GS} = 12$ V dc, condition A, pulsed (see 4.5.1), $I_D = I_{D2}$	$r_{DS(ON)1}$			
2N7475T1					0.0145	Ω
2N7476T1					0.044	Ω
2N7477T1					0.061	Ω
Forward voltage	4011	$V_{GS} = 0$, condition A, pulsed (see 4.5.1), $I_S = \text{rated } I_S$	V_{SD}			
2N7475T1					1.2	V dc
2N7476T1					1.2	V dc
2N7477T1					1.2	V dc

See footnotes at end of table.

TABLE I. Group A inspection - Continued.

Inspection <u>1/</u>	MIL-STD-750		Symbol	Limits		Unit
	Method	Condition		Min	Max	
<u>Subgroup 3</u>						
High temperature operation		$T_C = T_J = +125^\circ\text{C}$				
Gate current	3411	$V_{GS} = \pm 20\text{ V dc}$, bias condition C, $V_{DS} = 0$	I_{GSS2}		± 200	nA dc
Drain current	3413	$V_{GS} = 0$, bias condition C, $V_{DS} = 80$ percent of rated V_{DS}	I_{DSS2}		25	$\mu\text{A dc}$
Static drain to source on-state resistance	3421	$V_{GS} = 12\text{ V dc}$, condition A, pulsed (see 4.5.1), $I_D = I_{D2}$	$r_{DS(ON)3}$			
2N7475T1					0.029	Ω
2N7476T1					0.088	Ω
2N7477T1					0.134	Ω
Gate to source voltage (threshold)	3403	$V_{DS} \geq V_{GS}$, $I_D = 1\text{ mA dc}$	$V_{GS(TH)2}$	1.5		V dc
Low temperature operation		$T_C = T_J = -55^\circ\text{C}$				
Gate to source voltage (threshold)	3403	$V_{DS} \geq V_{GS(TH)3}$, $I_D = 1\text{ mA dc}$	$V_{GS(TH)3}$		5.5	V dc
<u>Subgroup 4</u>						
Forward transconductance	3475	$I_D = I_{D2}$, $V_{DD} = 15\text{ V dc}$ (see 4.5.1)	g_{FS}			
2N7475T1					36	S
2N7476T1					35	S
2N7477T1					27	S
Switching time test	3472	$I_D = I_{D1}$, $V_{GS} = 12\text{ V dc}$; $R_G = 2.35\ \Omega$, $V_{DD} = 50$ percent of rated V_{DS}				
Turn-on delay time			$t_{D(on)}$		35	ns
Rise time			t_r		125	ns
Turn-off delay time			$t_{D(off)}$		80	ns
Fall time			t_f			
2N7475T1					50	ns
2N7476T1					50	ns
2N7477T1					65	ns

See footnotes at end of table.

TABLE I. Group A inspection - Continued.

Inspection 1/	MIL-STD-750		Symbol	Limits		Unit
	Method	Condition		Min	Max	
<u>Subgroup 5</u>						
Safe operating area test (high voltage)	3474	See figure 4, $t_p = 10$ ms min. $V_{DS} = 80$ percent of max. rated V_{DS}				
Electrical measurements		See table I, subgroup 2				
<u>Subgroup 6</u>						
Not applicable						
<u>Subgroup 7</u>						
Gate charge	3471	Condition B; $I_D = I_{D1}$				
On-state gate charge			$Q_{G(ON)}$			
2N7475T1				160	nC	
2N7476T1				165	nC	
2N7477T1				165	nC	
Gate to source charge			Q_{GS}			
2N7475T1				55	nC	
2N7476T1				45	nC	
2N7477T1				45	nC	
Gate to drain charge			Q_{GD}			
2N7475T1				75	nC	
2N7476T1				75	nC	
2N7477T1				75	nC	
Reverse recovery time	3473	$di/dt = -100$ A/ μ s, $V_{DD} \leq 50$ V $I_D = I_{D1}$	t_{rr}			
2N7475T1				300	ns	
2N7476T1				450	ns	
2N7477T1				560	ns	

1/ For sampling plan, see MIL-PRF-19500.

2/ This test required for the following end-point measurements only:

- Group B, subgroups 3 and 4 (JANS).
- Group B, subgroups 2 and 3 (JANTXV).
- Group C, subgroup 2 and 6.
- Group E, subgroup 1.

MIL-PRF-19500/685E

TABLE II. Group D inspection.

Inspection 1/ 2/ 3/ 4/	MIL-STD-750		Symbol	Pre-irradiation limits		Post-irradiation limits		Unit
	Method	Conditions		R		R		
				Min	Max	Min	Max	
<u>Subgroup 1</u>								
Not applicable								
<u>Subgroup 2</u>		$T_C = + 25^\circ\text{C}$						
Steady-state total dose irradiation (V_{GS} bias) 5/	1019	$V_{GS} = 12 \text{ V}; V_{DS} = 0$						
Steady-state total dose irradiation (V_{DS} bias) 5/	1019	$V_{GS} = 0; V_{DS} = 80$ percent of rated V_{DS} (pre-irradiation)						
End-point electricals:								
Breakdown voltage, drain to source	3407	$V_{GS} = 0; I_D = 1 \text{ mA};$ bias condition C	$V_{(BR)DSS}$					
2N7475T1				130		130		V dc
2N7476T1				200		200		V dc
2N7477T1				250		250		V dc
Gate to source voltage (threshold)	3403	$V_{DS} \geq V_{GS}; I_D = 1 \text{ mA}$	$V_{GS(th)1}$	2.5	4.5	2.0	4.5	V dc
Gate current	3411	$V_{GS} = +20 \text{ V}, V_{DS} = 0;$ bias condition C	I_{GSSF1}		100		100	nA dc
Gate current	3411	$V_{GS} = -20 \text{ V}, V_{DS} = 0;$ bias condition C	I_{GSSR1}		-100		-100	nA dc
Drain current	3413	$V_{GS} = 0, V_{DS} = 80$ percent of rated V_{DS} (pre-irradiation); bias condition C	I_{DSS}		10		10	μA dc
Static drain to source on-state voltage	3405	$V_{GS} = 12 \text{ V};$ condition A, pulsed (see 4.5.1)	$V_{DS(on)}$					
2N7475T1		$I_D = 45 \text{ A}$ dc			0.630		0.630	V dc
2N7476T1		$I_D = 35 \text{ A}$ dc			1.715		1.715	V dc
2N7477T1		$I_D = 23.5 \text{ A}$ dc			1.434		1.434	V dc
Forward voltage source drain diode	4011	$V_{GS} = 0, I_D = I_{D1}$ bias condition C	V_{SD}					
2N7475T1		$I_S = 45 \text{ A}$ dc			1.2		1.2	V dc
2N7476T1		$I_S = 45 \text{ A}$ dc			1.2		1.2	V dc
2N7477T1		$I_S = 37 \text{ A}$ dc			1.2		1.2	V dc

1/ For sampling plan see MIL-PRF-19500.

2/ Group D qualification may be performed prior to lot formation. Wafers qualified to these group D QCI requirements may be used for any other specification sheets utilizing the same die design.

3/ At the manufacturer's option, group D samples need not be subjected to the screening tests, and may be assembled in its qualified package or in any qualified package that the manufacturer has data to correlate the performance to the designated package.

4/ The R designation represents devices which pass end-points at 100K rads (Si).

5/ Separate samples shall be pulled for each bias.

* TABLE III. Group E inspection (all quality levels) for qualification or re-qualification only.

Inspection	MIL-STD-750		Sample plan
	Method	Conditions	
<u>Subgroup 1</u>			45 devices c = 0
Temperature cycle	1051	Condition G, 500 cycles	
Hermetic seal	1071	As applicable	
Fine leak			
Gross leak			
Electrical measurements		See table I, subgroup 2	
<u>Subgroup 2 1/</u>			45 devices c = 0
Steady-state gate bias	1042	Condition B, 1,000 hours	
Electrical measurements		See table I, subgroup 2	
Steady-state reverse bias	1042	Condition A, 1,000 hours	
Electrical measurements		See table I, subgroup 2	
<u>Subgroup 4</u>			Sample size N/A
Thermal impedance curves		See MIL-PRF-19500	
<u>Subgroup 5</u>			3 devices c = 0
Barometric pressure 2N7477T1 only	1001	Condition C, $V_{(ISO)} = V_{DS}$; $V_{DS} = 250$ V dc	
<u>Subgroup 10</u>			
Commutating diode for safe operating area test procedure for measuring dv/dt during reverse recovery of power MOSFET transistors or insulated gate bipolar transistors	3476	Test conditions shall be derived by the manufacturer	22 devices c = 0

See footnotes at end of table.

* TABLE III. Group E inspection (all quality levels) for qualification or re-qualification only - Continued.

Inspection	MIL-STD-750		Sample plan
	Method	Conditions	
<u>Subgroup 11</u>			3 devices
* SEE <u>2/ 3/ 4/</u> Electrical measurements <u>5/</u> SEE irradiation	1080	See figure 5 I_{GSSF1} , I_{GSSR1} , and I_{DSS1} in accordance with table I, subgroup 2 Fluence = $3E5 \pm 20$ percent ions/cm ² , flux = $2E3$ to $2E4$ ions/cm ² /sec, temperature = $25 \pm 5^\circ C$ Surface LET = $38 \text{ MeV}\cdot\text{cm}^2/\text{mg} \pm 5\%$ range = $38 \mu\text{m} \pm 7.5\%$, energy = $300 \text{ MeV} \pm 7.5\%$	
2N7475T1		In situ bias conditions: $V_{DS} = 130 \text{ V}$ and $V_{GS} = -20 \text{ V}$, (typical 3.75 MeV/nucleon at Texas A & M Cyclotron)	
2N7476T1		In situ bias conditions: $V_{DS} = 200 \text{ V}$ and $V_{GS} = -20 \text{ V}$, (nominal 3.86 MeV/nucleon at Brookhaven National Lab Accelerator)	
2N7477T1		In situ bias conditions: $V_{DS} = 250 \text{ V}$ and $V_{GS} = -20 \text{ V}$, (nominal 3.86 MeV/nucleon at Brookhaven National Lab Accelerator) Surface LET = $61 \text{ MeV}\cdot\text{cm}^2/\text{mg} \pm 5\%$, range = $31 \mu\text{m} \pm 10\%$, energy = $330 \text{ MeV} \pm 7.5\%$	
2N7475T1		In situ bias conditions: $V_{DS} = 130 \text{ V}$ and $V_{GS} = -10 \text{ V}$, $V_{DS} = 100 \text{ V}$ and $V_{GS} = -15 \text{ V}$, $V_{DS} = 50 \text{ V}$ and $V_{GS} = -20 \text{ V}$, (typical 2.70 MeV/nucleon at Texas A & M Cyclotron)	
2N7476T1		In situ bias conditions: $V_{DS} = 200 \text{ V}$ and $V_{GS} = -10 \text{ V}$, $V_{DS} = 185 \text{ V}$ and $V_{GS} = -15 \text{ V}$, $V_{DS} = 120 \text{ V}$ and $V_{GS} = -20 \text{ V}$, (nominal 2.92 MeV/nucleon at Brookhaven National Lab Accelerator)	
2N7477T1		In situ bias conditions: $V_{DS} = 250 \text{ V}$ and $V_{GS} = -15 \text{ V}$, $V_{DS} = 240 \text{ V}$ and $V_{GS} = -20 \text{ V}$, (nominal 2.92 MeV/nucleon at Brookhaven National Lab Accelerator)	

See footnotes at end of table.

* TABLE III. Group E inspection (all quality levels) for qualification or re-qualification only - Continued.

Inspection	MIL-STD-750		Sample plan
	Method	Conditions	
<u>Subgroup 11</u> - continued		Surface LET = 84 MeV-cm ² /mg ±5%, range = 28 μm ±7.5%, energy = 350 MeV ±7.5%	3 devices
2N7475T1		In situ bias conditions: V _{DS} = 130 V and V _{GS} = 0 V, V _{DS} = 120 V and V _{GS} = -5 V, V _{DS} = 30 V and V _{GS} = -10 V, (typical 1.89 MeV/nucleon at Texas A & M Cyclotron)	
2N7476T1		In situ bias conditions: V _{DS} = 200 V and V _{GS} = -5V, V _{DS} = 150 V and V _{GS} = -10 V, V _{DS} = 50 V and V _{GS} = -15 V, V _{DS} = 25 V and V _{GS} = -20 V, (nominal 1.98 MeV/nucleon at Brookhaven National Lab Accelerator)	
2N7477T1		In situ bias conditions: V _{DS} = 250 V and V _{GS} = -5V, V _{DS} = 225 V and V _{GS} = -10 V, V _{DS} = 175 V and V _{GS} = -15 V, V _{DS} = 50 V and V _{GS} = -20 V, (nominal 1.98 MeV/nucleon at Brookhaven National Lab Accelerator)	
Electrical measurements <u>5</u> /		I _{GSSF1} , I _{GSSR1} , and I _{DSS1} in accordance with table I, subgroup 2	

- 1/ A separate sample for each test shall be pulled.
- 2/ Group E qualification of SEE testing may be performed prior to lot formation. Qualification may be extended to other specification sheets utilizing the same structurally identical die design.
- 3/ Device qualification to a higher level LET is sufficient to qualify all lower level LETs.
- 4/ The sampling plan applies to each bias condition.
- 5/ Examine I_{GSSF1}, I_{GSSR1}, and I_{DSS1} before and following SEE irradiation to determine acceptability for each bias condition. Other test conditions in accordance with table I, subgroup 2, may be performed at the manufacturer's option.

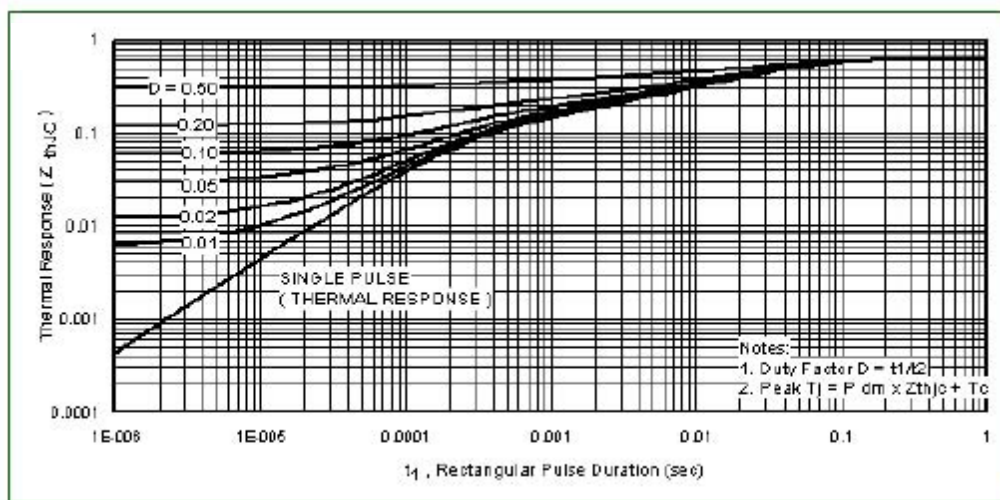


FIGURE 2. Thermal impedance curve.

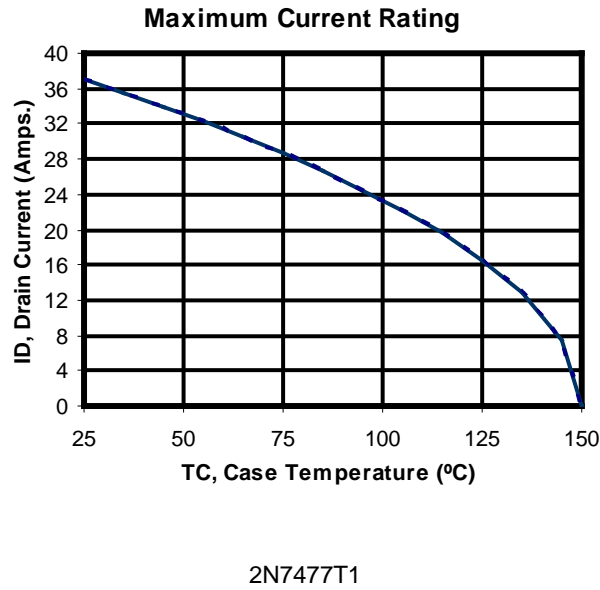
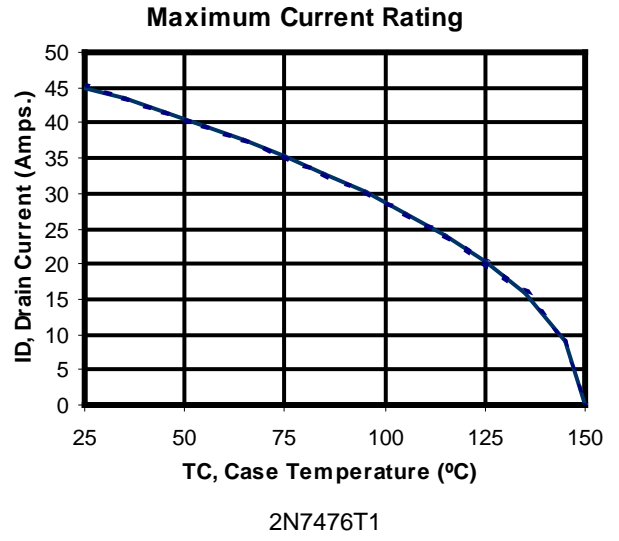
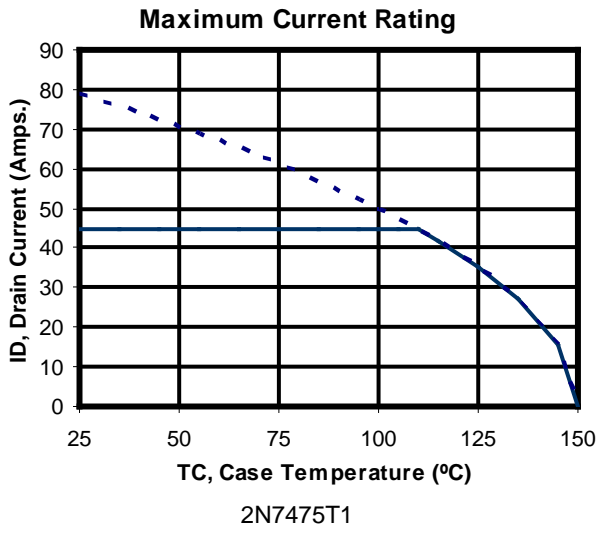
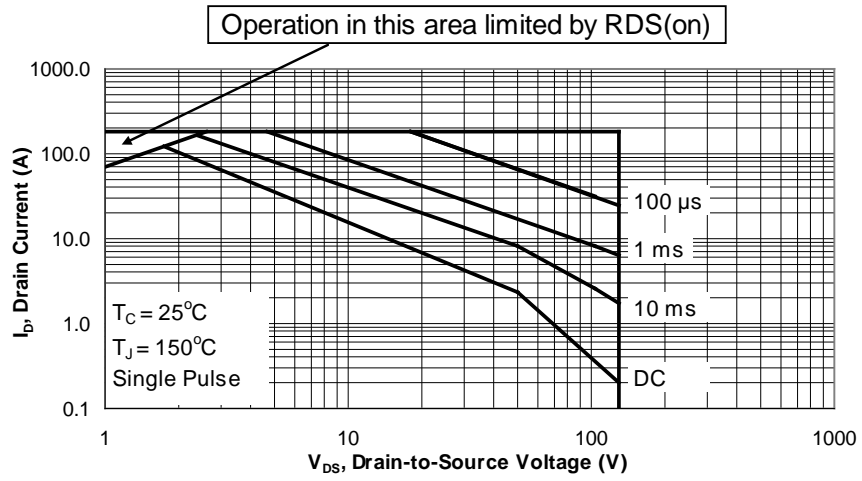
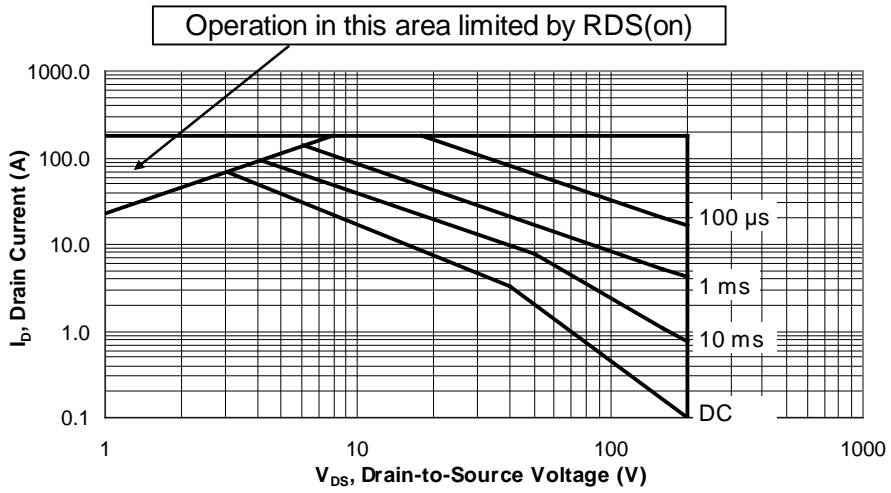


FIGURE 3. Maximum drain current versus case temperature graphs.

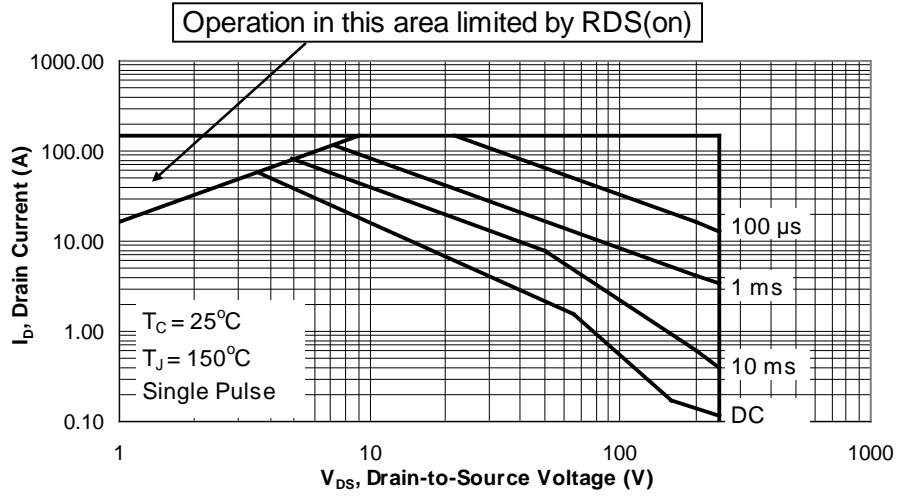


2N7475T1



2N7476T1

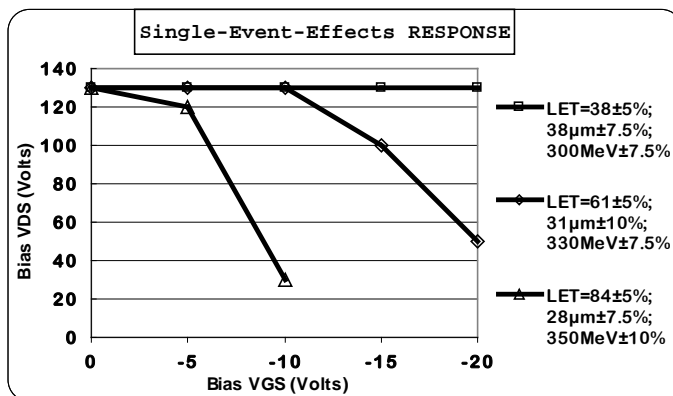
FIGURE 4. Safe operating area graphs.



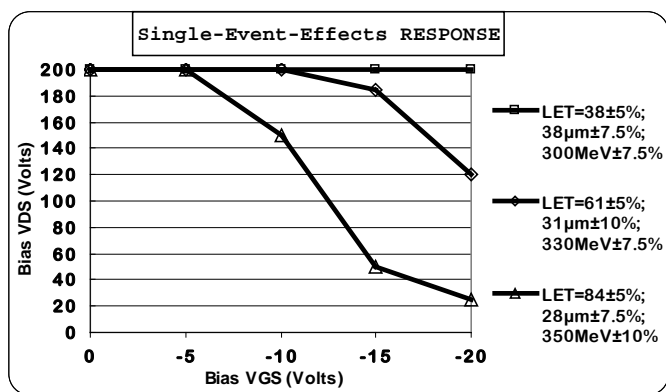
2N7477T1

FIGURE 4. Safe operating area graphs - Continued.

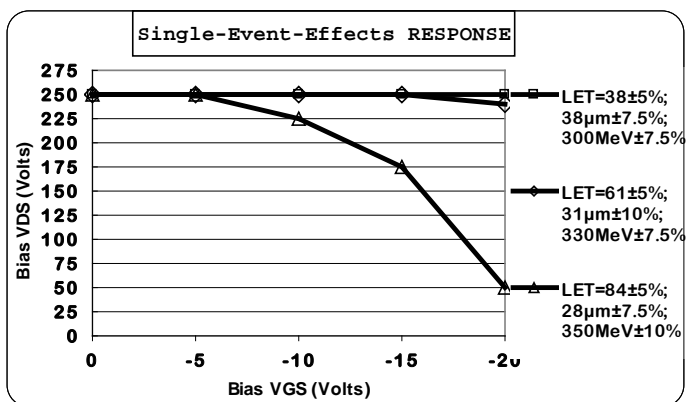
2N7475T1



2N7476T1



2N7477T1



* FIGURE 5. Typical SEE safe operating area graph.

5. PACKAGING

5.1 Packaging. For acquisition purposes, the packaging requirements shall be as specified in the contract or order (see 6.2). When packaging of materiel is to be performed by DoD or in-house contractor personnel, these personnel need to contact the responsible packaging activity to ascertain packaging requirements. Packaging requirements are maintained by the Inventory Control Point's packaging activities within the Military Service or Defense Agency, or within the Military Service's system commands. Packaging data retrieval is available from the managing Military Department's or Defense Agency's automated packaging files, CD-ROM products, or by contacting the responsible packaging activity.

6. NOTES

(This section contains information of a general or explanatory nature that may be helpful, but is not mandatory. The notes specified in MIL-PRF-19500 are applicable to this specification.)

6.1 Intended use. Semiconductors conforming to this specification are intended for original equipment design applications and logistic support of existing equipment.

6.2 Acquisition requirements. Acquisition documents should specify the following:

- a. Title, number, and date of this specification.
- b. Packaging requirements (see 5.1).
- c. Lead formation and finish (see 3.4.1).
- d. Product assurance level and type designator.

* 6.3 Qualification. With respect to products requiring qualification, awards will be made only for products which are, at the time of award of contract, qualified for inclusion in Qualified Manufacturers List (QML 19500) whether or not such products have actually been so listed by that date. The attention of the contractors is called to these requirements, and manufacturers are urged to arrange to have the products that they propose to offer to the Federal Government tested for qualification in order that they may be eligible to be awarded contracts or orders for the products covered by this specification. Information pertaining to qualification of products may be obtained from Defense Supply Center, Columbus, ATTN: DSCC/VQE, P.O. Box 3990, Columbus, OH 43218-3990 or e-mail vqe.chief@dla.mil. An online listing of products qualified to this specification may be found in the Qualified Products Database (QPD) at <https://assist.daps.dla.mil>.

6.4 Cross-reference list. The following table shows the generic P/N and its associated military P/N (without JAN and RHA prefix).

Generic P/N	Military P/N
IRHMS57163SE	2N7475T1
IRHMS57260SE	2N7476T1
IRHMS57264SE	2N7477T1

6.5 JANC die versions. The JANHC and JANKC die versions of these devices are covered under specification sheet MIL-PRF-19500/741.

6.6 Changes from previous issue. The margins of this specification are marked with asterisks to indicate where changes from the previous issue were made. This was done as a convenience only and the Government assumes no liability whatsoever for any inaccuracies in these notations. Bidders and contractors are cautioned to evaluate the requirements of this document based on the entire content irrespective of the marginal notations and relationship to the last previous issue.

Custodians:
Army - CR
Navy - EC
Air Force - 85
NASA - NA
DLA - CC

Preparing activity:
DLA - CC

(Project 5961-2010-015)

Review activity:
Air Force - 99

* NOTE: The activities listed above were interested in this document as of the date of this document. Since organizations and responsibilities can change, you should verify the currency of the information above using the ASSIST Online database at <https://assist.daps.dla.mil/> .